

## N-Channel Enhancement Mode MOSFET

### 1. Product Information

#### 1.1 Features

- Advanced trench cell design
- Low Thermal Resistance
- Super Trench

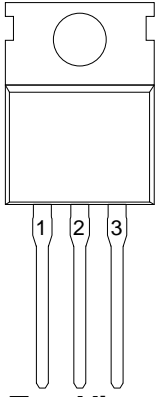
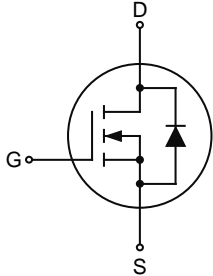
#### 1.2 Applications

- Motor drivers
- DC/DC Converter

#### 1.3 Quick reference

- $BV \geq 100\text{ V}$
- $R_{DS(ON)} \leq 2.0\text{ m}\Omega @V_{GS} = 10\text{ V}$
- $P_{tot} \leq 147\text{ W}$
- $R_{DS(ON)} \leq 2.5\text{ m}\Omega @V_{GS} = 6\text{ V}$
- $I_D \leq 120\text{ A}$

### 2. Pin Description

Pin	Description	Simplified Outline	Symbol
1	Gate(G)	 <p>Top View TO-220</p>	
2	Drain(D)		
3	Source(S)		

## 3. Limiting Values

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DS}$	Drain-Source Voltage	$T_C=25^{\circ}C$	-	100	V
$V_{GS}$	Gate-Source Voltage	$T_C=25^{\circ}C$	-	$\pm 20$	V
$I_D^{*,***}$	Drain Current (DC)	$T_C=25^{\circ}C, V_{GS}=10\text{ V}$	-	120	A
		$T_C=100^{\circ}C, V_{GS}=10\text{ V}$	-	117	A
$I_{DM}^*$	Drain Current (Pulsed)	$T_C=25^{\circ}C, V_{GS}=10\text{ V}$	-	360	A
$P_{tot}$	Drain power dissipation	$T_C=25^{\circ}C$	-	250	W
$I_S$	Continuous-Source Current	$T_C=25^{\circ}C$	-	180	A
$E_{AS}$	Single Pulsed Avalanche Energy	$V_{DD}=40\text{ V}, L=1.0\text{ mH}$	-	1512	mJ
$T_J, T_{stg}$	Operating Junction and Storage Temperature Range		-55	150	$^{\circ}C$
$R_{\theta JA}^{**}$	Thermal Resistance-Junction to Ambient		-	42	$^{\circ}C/W$
$R_{\theta JC}^{**}$	Thermal Resistance-Junction to Case		-	0.5	

Notes:

- \* Pulse width  $\leq 300\ \mu s$ , duty cycle  $\leq 2\%$ .
- \*\* Surface Mounted on 1 in<sup>2</sup> pad area,  $t \leq 10\text{ sec}$ .
- \*\*\* Limited by bonding wire.

## 4. Marking Information

Product Name	Marking
KJ010N04C	<div style="display: inline-block; background-color: black; color: white; padding: 2px;">010N04 YWWXXX</div> <span style="margin-left: 10px;">YWWXXX: Date Code</span>

## 5. Ordering Code

Product Name	Package	Reel Size	Tape width	Quantity	Note
KJ010N04C	TO-220	-	-	50	

Note: KUAJIEXIN defines "Green" as lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900 ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500 ppm by weight; Follow IEC 61249-2-21 and IPC/JEDEC J-STD-020C)

## 6. Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

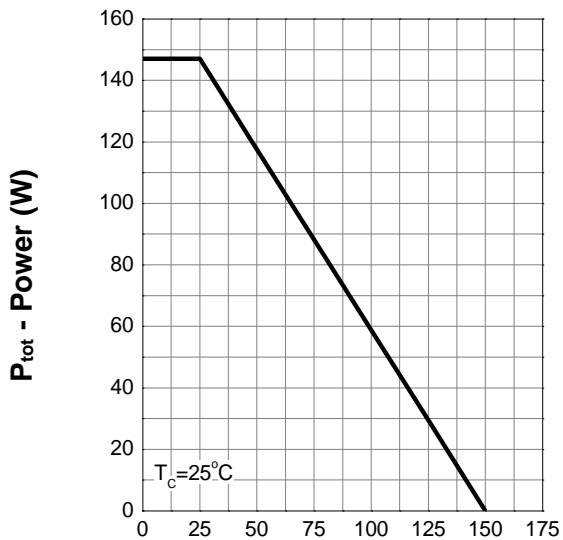
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0 V, I <sub>D</sub> =250 μA	100	-	-	V
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250 μA	2	-	4	V
I <sub>DSS</sub>	Zero Gate Voltage Source Current	V <sub>DS</sub> =80 V, V <sub>GS</sub> =0 V	-	-	1	μA
I <sub>GSS</sub>	Gate Leakage Current	V <sub>GS</sub> =±20 V, V <sub>DS</sub> =0 V	-	-	± 100	nA
R <sub>DS(ON)</sub> <sup>a</sup>	Drain-Source On-State Resistance	V <sub>GS</sub> =10 V, I <sub>D</sub> =50 A	-	1.7	2.0	mΩ
	Drain-Source On-State Resistance	V <sub>GS</sub> =6 V, I <sub>D</sub> =30 A	-	2.2	2.5	mΩ
<b>Diode Characteristics</b>						
V <sub>SD</sub> <sup>a</sup>	Diode Forward Voltage	I <sub>SD</sub> =50 A, V <sub>GS</sub> =0 V	-	-	1.3	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>SD</sub> =50 A, dI <sub>SD</sub> /dt=100 A/μs	-	122	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge		-	341	-	nC
<b>Dynamic Characteristics<sup>b</sup></b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0 V, V <sub>DS</sub> =50 V, Frequency=1 MHz	-	13427	-	pF
C <sub>oss</sub>	Output Capacitance		-	2037	-	
C <sub>rss</sub>	Reverse Transfer Capacitance		-	46	-	
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DS</sub> =50 V, V <sub>GEN</sub> =10 V, R <sub>G</sub> =3.9 Ω, R <sub>L</sub> =1 Ω, I <sub>D</sub> =50 A	-	38	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	124	-	
t <sub>d(off)</sub>	Turn-off Delay Time		-	152	-	
t <sub>f</sub>	Turn-off Fall Time		-	127	-	
<b>Gate Charge Characteristics<sup>b</sup></b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> =10 V, V <sub>DS</sub> =50 V, I <sub>DS</sub> =50 A	-	242	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	72	-	
Q <sub>gd</sub>	Gate-Drain Charge		-	65	-	

Notes:

- Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.
- Guaranteed by design, not subject to production testing.

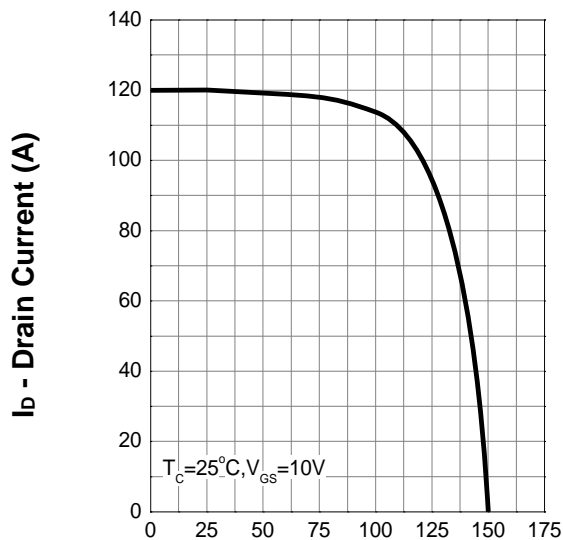
## 7. Typical Characteristics

### Power Capability



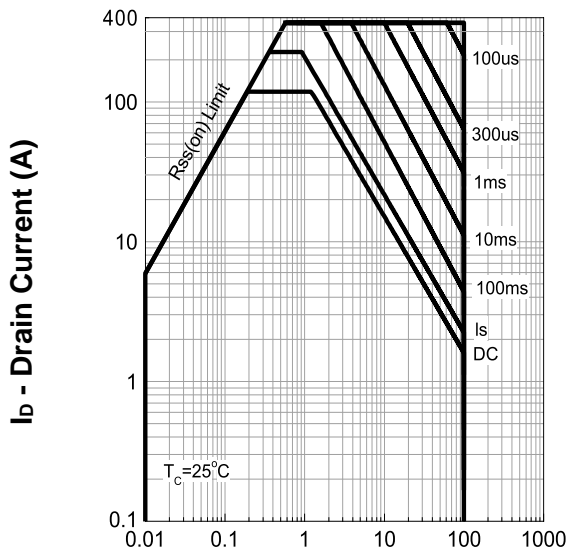
T<sub>j</sub> - Junction Temperature (°C)

### Current Capability



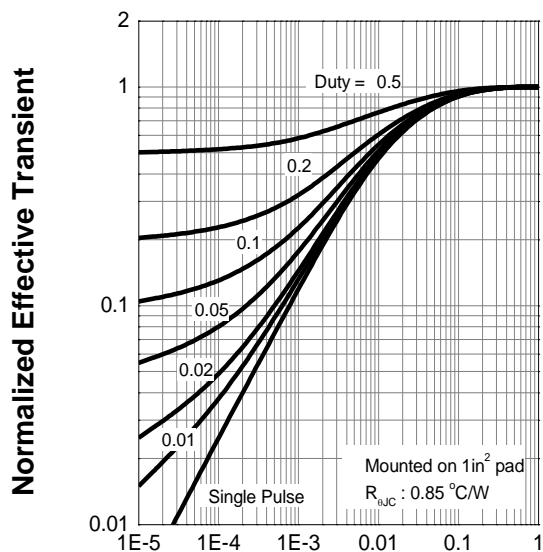
T<sub>j</sub> - Junction Temperature (°C)

### Safe Operation Area



V<sub>DS</sub> - Drain-Source Voltage (V)

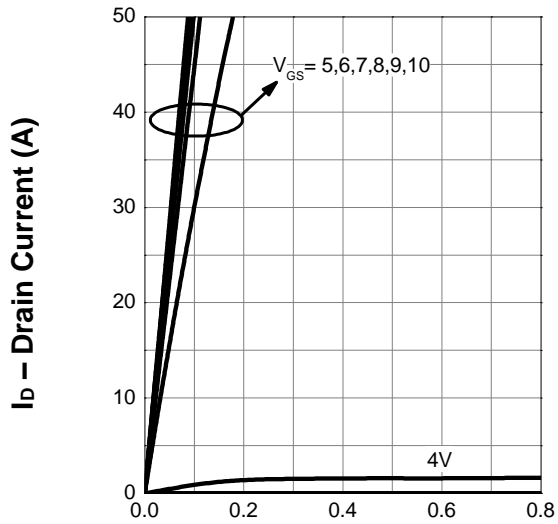
### Thermal Transient Impedance



Square Wave Pulse Duration (sec)

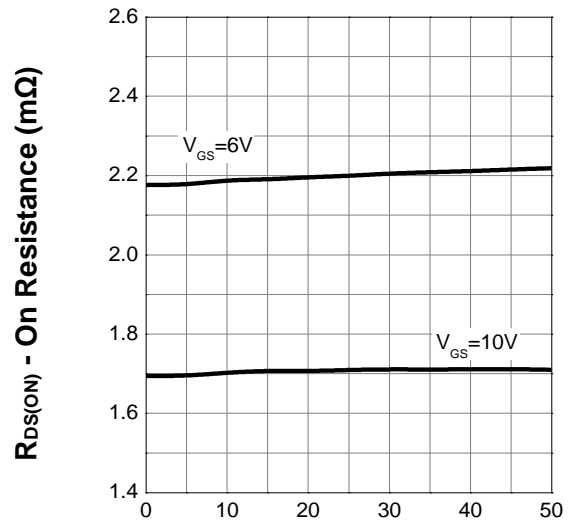
## 7. Typical Characteristics (cont.)

**Output Characteristics**



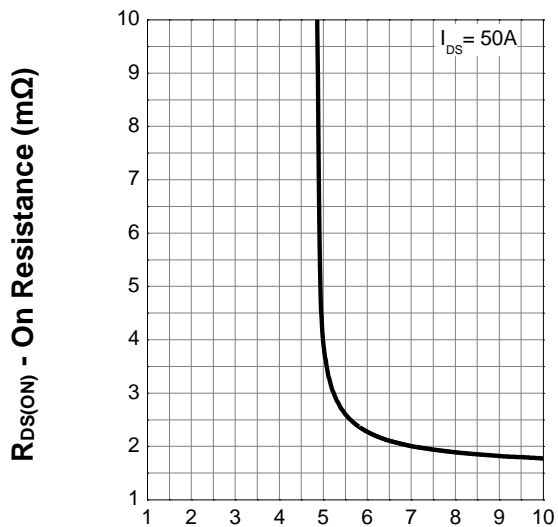
$V_{DS}$  - Drain-Source Voltage (V)

**Drain-Source On Resistance**



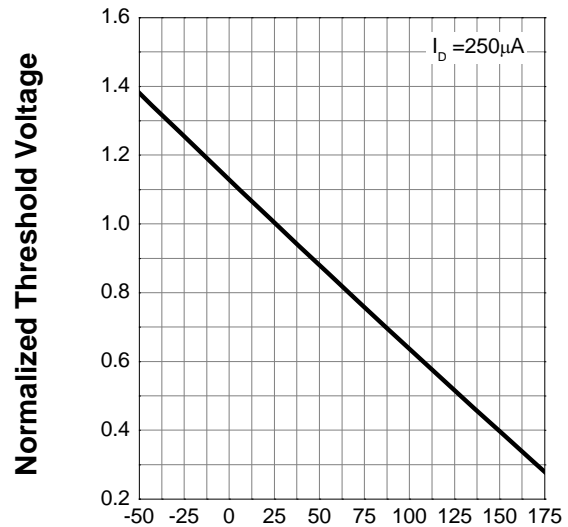
$I_D$  - Drain Current (A)

**Transfer Characteristics**



$V_{GS}$  - Gate-Source Voltage (V)

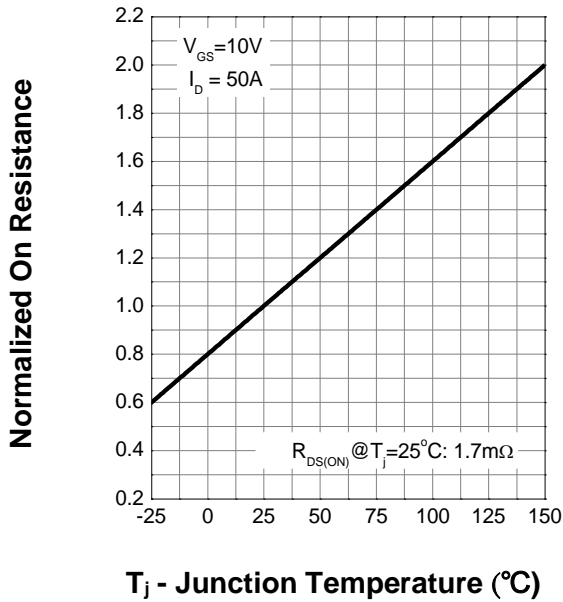
**Gate Threshold Voltage**



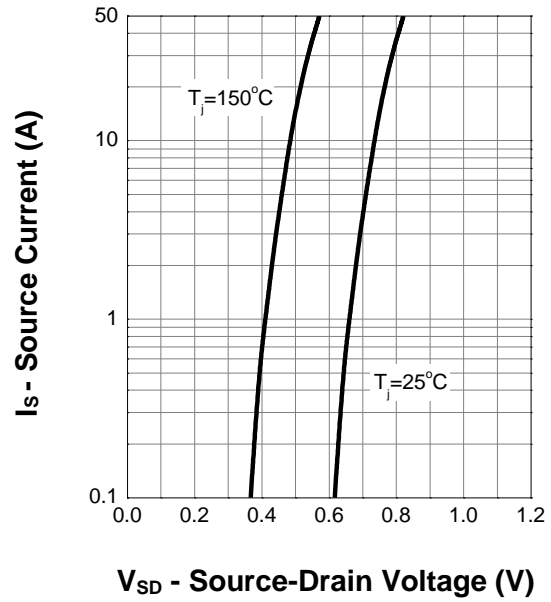
$T_j$  - Junction Temperature ( $^{\circ}C$ )

## 7. Typical Characteristics (cont.)

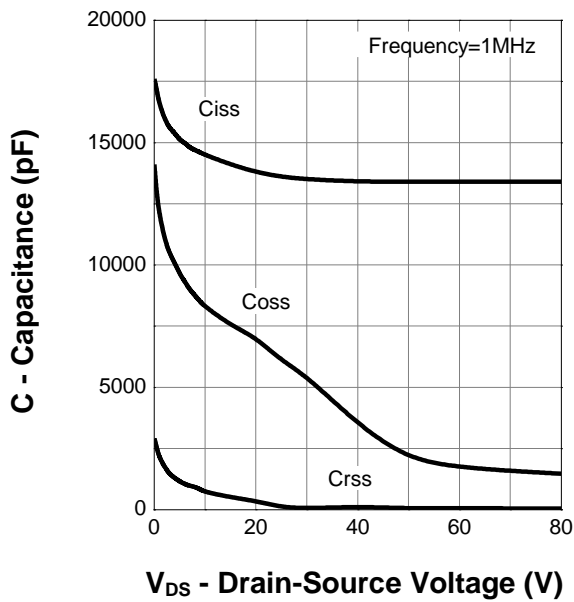
### Drain-Source On Resistance



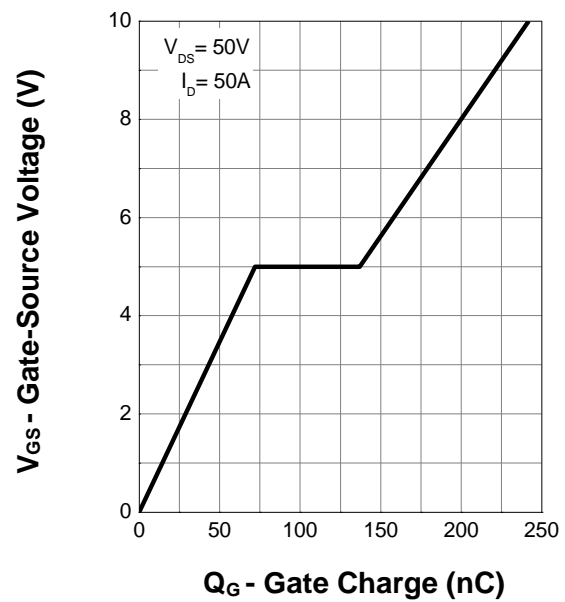
### Body Diode Characteristics



### Capacitance

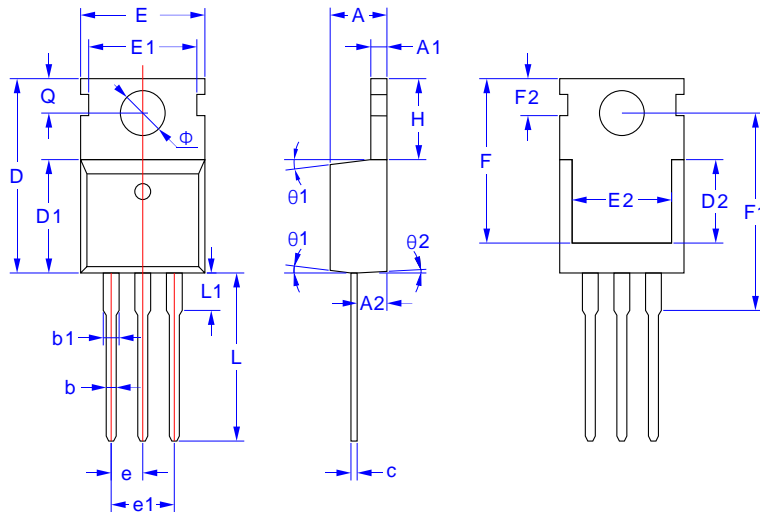


### Gate Charge



## 8. Package Dimensions

### TO-220 Package



Symbol	Dimensions in Millimeters		
	MIN.	NOM.	MAX.
A	4.27	4.57	4.87
A1	1.15	1.30	1.45
A2	2.10	2.40	2.70
b	0.70	0.80	1.00
b1	1.17	1.27	1.50
c	0.40	0.50	0.65
D	15.50	15.80	16.10
D1	8.80	9.10	9.40
D2	5.70	6.70	7.00
E	9.70	10.00	10.30
E1	-	8.70	-
E2	7.00	8.00	8.40
e	2.54		
e1	5.08		
F	13.30	13.50	13.70
F1	15.50	15.90	16.30
F2	2.80	3.00	3.20
H	6.00	6.50	6.85
L	12.75	13.50	13.90
L1	-	3.10	3.40
Q	2.60	2.80	3.00
Φ	3.45	3.60	3.75
θ1	4°	7°	10°
θ2	0°	3°	6°